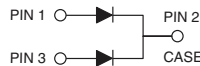
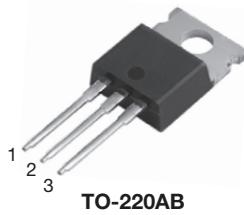


Dual High Voltage TMBS[®] (Trench MOS Barrier Schottky) Rectifier

 Ultra Low $V_F = 0.29\text{ V}$ at $I_F = 5.0\text{ A}$


PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 30 A
V_{RRM}	60 V
I_{FSM}	300 A
V_F at $I_F = 30\text{ A}$ ($T_J = 125\text{ °C}$)	0.51 V
T_J max.	150 °C
Package	TO-220AB
Circuit configuration	Common cathode

FEATURES

- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency operation
- Solder bath temperature 275 °C maximum, 10 s per JESD 22-B106
- AEC-Q101 qualified available:
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

MECHANICAL DATA

Case: TO-220AB

Molding compound meets UL 94 V-0 flammability rating
 Base P/N-M3 - halogen-free, RoHS-compliant
 Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Mounting torque: 10 in-lbs maximum

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VX6060C	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	60	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$	per device	60
		per diode	30
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	300	A
Operating junction temperature range	T_J ⁽¹⁾	-40 to +150	°C
Storage temperature range	T_{STG}	-40 to +150	

Note

⁽¹⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I _F = 5 A	T _J = 25 °C	V _F ⁽¹⁾	0.41	-	V
	I _F = 15 A			0.48	-	
	I _F = 30 A			0.56	0.62	
	I _F = 5 A	T _J = 125 °C		0.29	-	
	I _F = 15 A			0.39	-	
	I _F = 30 A			0.51	0.56	
Reverse current at rated V _R per diode	V _R = 60 V	T _J = 25 °C	I _R ⁽²⁾	-	3.5	mA
		T _J = 125 °C		30	100	
Typical junction capacitance	4.0 V, 1 MHz		C _J	3800	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	VX6060C	UNIT
Typical thermal resistance per device	R _{θJC} ⁽¹⁾	1	°C/W

Note

- (1) Thermal resistance junction-to-case to follow JEDEC[®] 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
VX6060C-M3/P	2.04	P	50/tube	Tube
VX6060CHM3/P ⁽¹⁾	2.04	P	50/tube	Tube

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

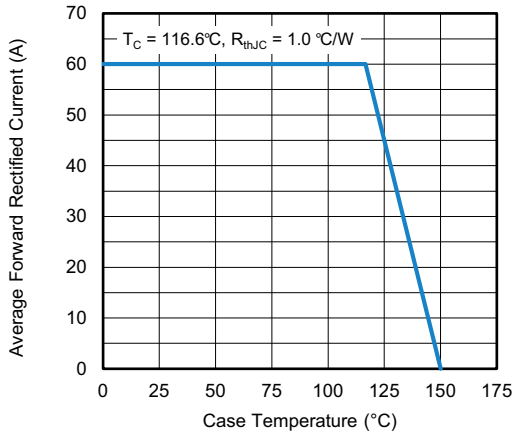


Fig. 1 - Maximum Forward Current Derating Curve

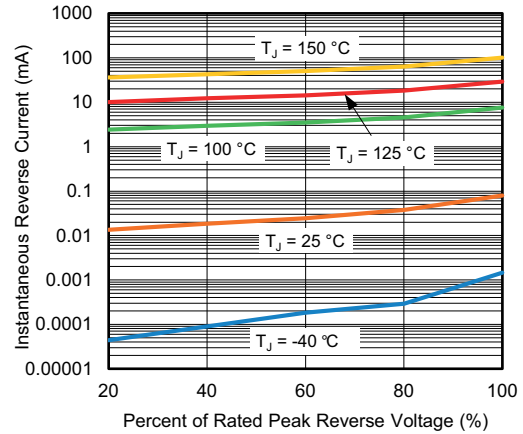


Fig. 4 - Typical Reverse Leakage Characteristics

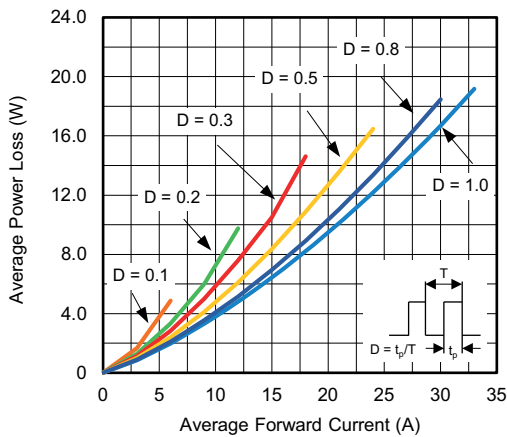


Fig. 2 - Average Power Loss Characteristics

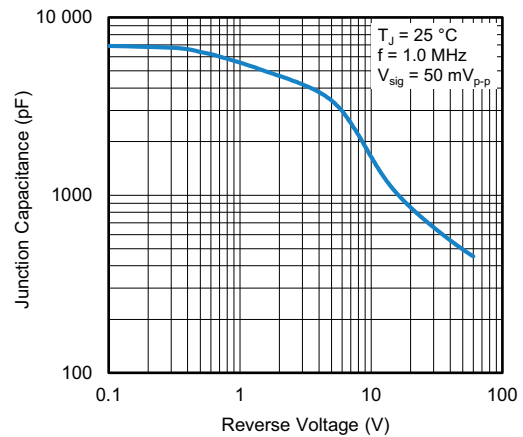


Fig. 5 - Typical Junction Capacitance

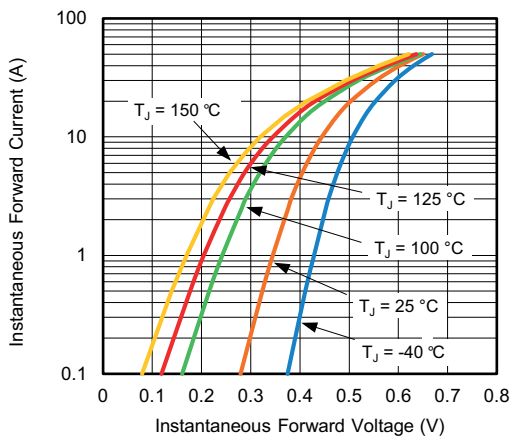


Fig. 3 - Typical Instantaneous Forward Characteristics

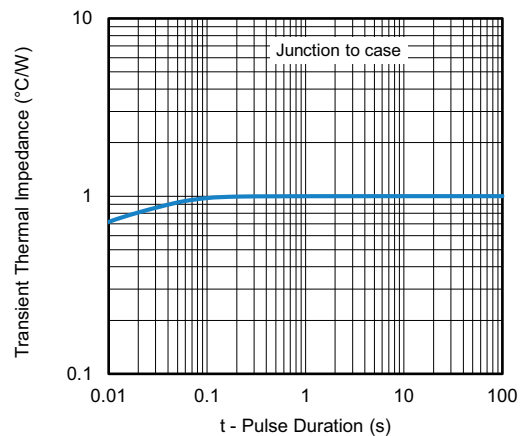
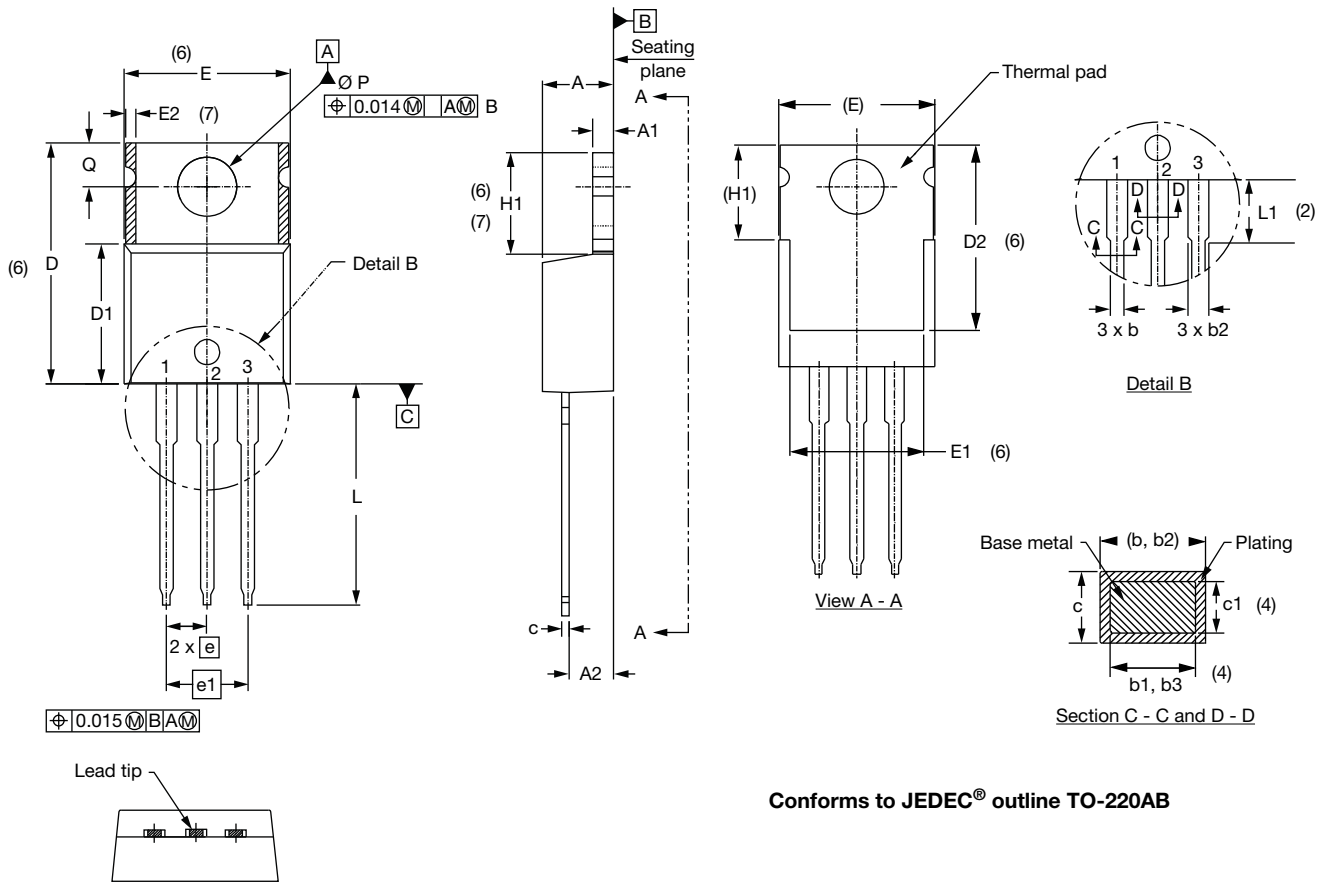


Fig. 6 - Typical Transient Thermal Impedance

DIMENSIONS in millimeters (inches) **TO-220AB**


Conforms to JEDEC® outline TO-220AB

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	5.84	6.86	0.230	0.270	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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